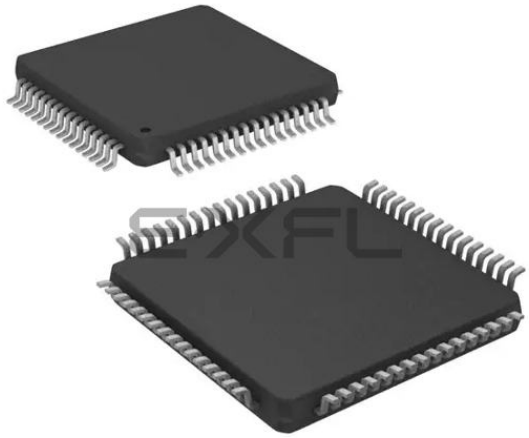

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	54
Program Memory Size	128KB (64K x 16)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	3.8K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 12x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf6723-i-pt

PIC18F8723 FAMILY

64/80-Pin, 1-Mbit, Enhanced Flash Microcontrollers with 12-Bit A/D and nanoWatt Technology

Peripheral Highlights:

- 12-Bit, Up to 16-Channel Analog-to-Digital Converter module (A/D):
  - Auto-acquisition capability
  - Conversion available during Sleep
- Two Master Synchronous Serial Port (MSSP) modules supporting 2/3/4-Wire SPI (all four modes) and I^2C™ Master and Slave modes
- Two Capture/Compare/PWM (CCP) modules
- Three Enhanced Capture/Compare/PWM (ECCP) modules:
  - One, two or four PWM outputs
  - Selectable polarity
  - Programmable dead time
  - Auto-shutdown and auto-restart
- Two Enhanced Addressable USART modules:
  - Supports RS-485, RS-232 and LIN 1.2
  - Auto-wake-up on Start bit
  - Auto-Baud Detect
- Dual Analog Comparators with Input Multiplexing
- High-Current Sink/Source 25 mA/25 mA
- Four Programmable External Interrupts
- Four Input Change Interrupts

External Memory Interface:

- Address Capability of Up to 2 Mbytes
- 8-Bit or 16-Bit Interface
- 8, 12, 16 and 20-Bit Address modes

Power-Managed Modes:

- Run: CPU on, Peripherals on
- Idle: CPU off, Peripherals on
- Sleep: CPU off, Peripherals off
- Idle mode Currents Down to 15 μA Typical
- Sleep Current Down to 0.2 μA Typical
- Timer1 Oscillator: 1.8 μA, 32 kHz, 2V
- Watchdog Timer: 2.1 μA

Special Microcontroller Features:

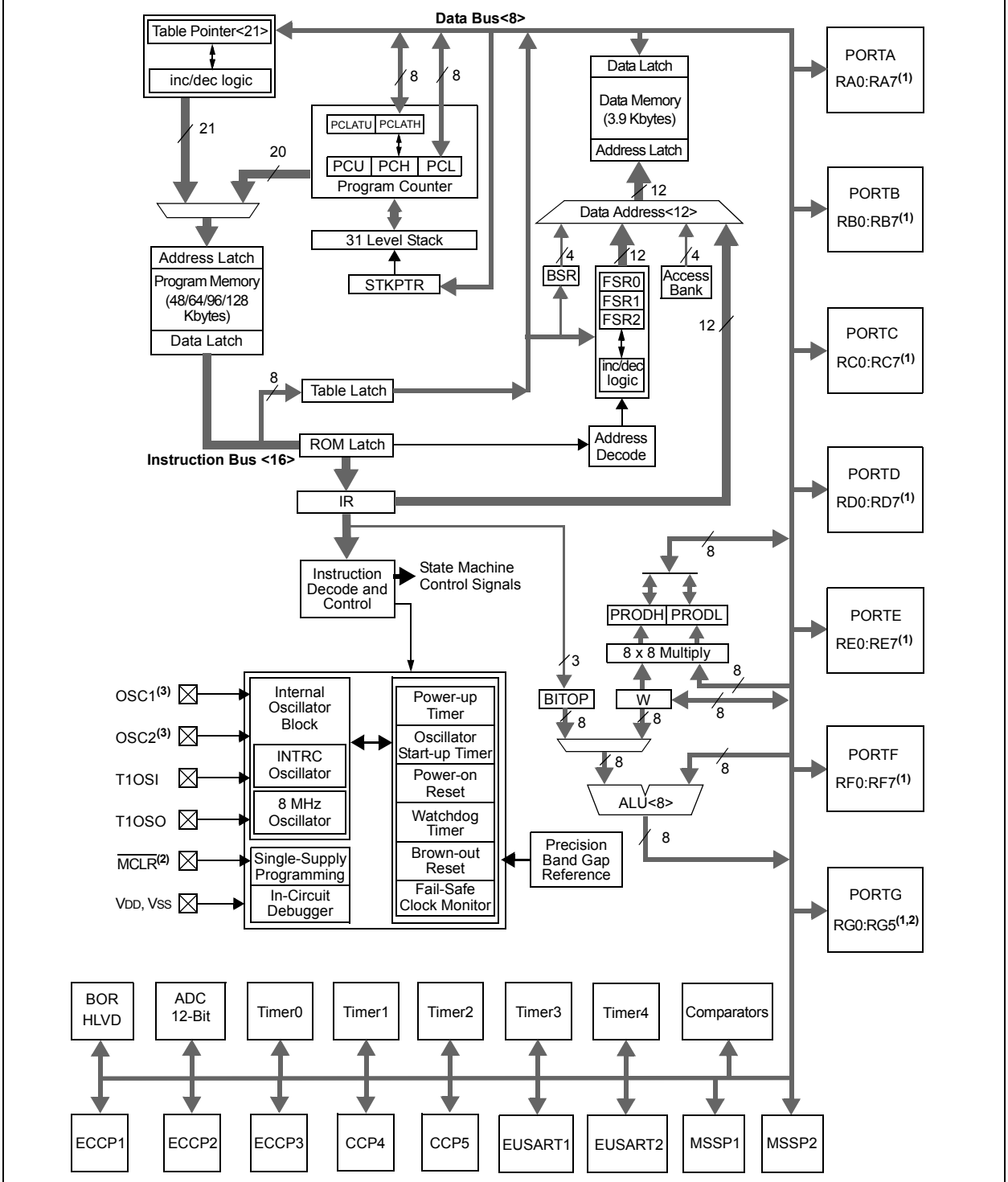
- C Compiler Optimized Architecture:
  - Optional extended instruction set designed to optimize re-entrant code
- 100,000 Erase/Write Cycle Enhanced Flash Program Memory Typical
- 1,000,000 Erase/Write Cycle Data EEPROM Memory Typical
- Flash/Data EEPROM Retention: 100 Years Typical
- Self-Programmable under Software Control
- Priority Levels for Interrupts
- 8 x 8 Single-Cycle Hardware Multiplier
- Extended Watchdog Timer (WDT):
  - Programmable period from 4 ms to 131s
- Single-Supply In-Circuit Serial Programming™ (ICSP™) via Two Pins
- In-Circuit Debug (ICD) via Two Pins
- Wide Operating Voltage Range: 2.0V to 5.5V
- Fail-Safe Clock Monitor
- Two-Speed Oscillator Start-up
- nanoWatt Technology

Note: This document is supplemented by the *"PIC18F8722 Family Data Sheet"* (DS39646). See **Section 1.0 "Device Overview"**.

Device	Program Memory		Data Memory		I/O	12-Bit A/D (ch)	CCP/ ECCP (PWM)	MSSP			EUSART	Comparators	Timers 8/16-Bit	External Bus
	Flash (bytes)	# Single-Word Instructions	SRAM (bytes)	EEPROM (bytes)					SPI	Master I^2C™				
PIC18F6628	96K	49152	3936	1024	54	12	2/3	2	Y	Y	2	2	2/3	N
PIC18F6723	128K	65536	3936	1024	54	12	2/3	2	Y	Y	2	2	2/3	N
PIC18F8628	96K	49152	3936	1024	70	16	2/3	2	Y	Y	2	2	2/3	Y
PIC18F8723	128K	65536	3936	1024	70	16	2/3	2	Y	Y	2	2	2/3	Y

NOTES:

FIGURE 1-1: PIC18F6628/6723 (64-PIN) BLOCK DIAGRAM



Note 1: See Table 1-2 for I/O port pin descriptions.

2: RG5 is only available when $\overline{\text{MCLR}}$ functionality is disabled.

3: OSC1/CLKI and OSC2/CLKO are only available in select oscillator modes and when these pins are not being used as digital I/O. For additional information, refer to **Section 2.0 "Oscillator Configurations"** of the *"PIC18F8722 Family Data Sheet"* (DS39646).

TABLE 1-2: PIC18F6628/6723 (64-PIN) PINOUT I/O DESCRIPTIONS

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
RG5/$\overline{MCLR}$/V_{PP}	7			Master Clear (input) or programming voltage (input).
RG5		I	ST	Digital input.
$\overline{MCLR}$		I	ST	Master Clear (Reset) input. This pin is an active-low Reset to the device.
V_{PP}		P		Programming voltage input.
OSC1/CLKI/RA7	39			Oscillator crystal or external clock input.
OSC1		I	ST	Oscillator crystal input or external clock source input. ST buffer when configured in RC mode, CMOS otherwise.
CLKI		I	CMOS	External clock source input. Always associated with pin function OSC1. (See related OSC1/CLKI, OSC2/CLKO pins.)
RA7		I/O	TTL	General purpose I/O pin.
OSC2/CLKO/RA6	40			Oscillator crystal or clock output.
OSC2		O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode.
CLKO		O	—	In RC mode, OSC2 pin outputs CLKO, which has 1/4 the frequency of OSC1 and denotes the instruction cycle rate.
RA6		I/O	TTL	General purpose I/O pin.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; I^2C™ = I^2C/SMBus input buffer

Note 1: Default assignment for ECCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for ECCP2 when Configuration bit, CCP2MX, is cleared.

TABLE 1-2: PIC18F6628/6723 (64-PIN) PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTD is a bidirectional I/O port.
RD0/PSP0	58			
RD0		I/O	ST	Digital I/O.
PSP0		I/O	TTL	Parallel Slave Port data.
RD1/PSP1	55			
RD1		I/O	ST	Digital I/O.
PSP1		I/O	TTL	Parallel Slave Port data.
RD2/PSP2	54			
RD2		I/O	ST	Digital I/O.
PSP2		I/O	TTL	Parallel Slave Port data.
RD3/PSP3	53			
RD3		I/O	ST	Digital I/O.
PSP3		I/O	TTL	Parallel Slave Port data.
RD4/PSP4/SDO2	52			
RD4		I/O	ST	Digital I/O.
PSP4		I/O	TTL	Parallel Slave Port data.
SDO2		O	—	SPI data out.
RD5/PSP5/SDI2/ SDA2	51			
RD5		I/O	ST	Digital I/O.
PSP5		I/O	TTL	Parallel Slave Port data.
SDI2		I	ST	SPI data in.
SDA2		I/O	I^2C/SMB	I^2C™ data I/O.
RD6/PSP6/SCK2/ SCL2	50			
RD6		I/O	ST	Digital I/O.
PSP6		I/O	TTL	Parallel Slave Port data.
SCK2		I/O	ST	Synchronous serial clock input/output for SPI mode.
SCL2		I/O	I^2C/SMB	Synchronous serial clock input/output for I^2C mode.
RD7/PSP7/$\overline{SS2}$	49			
RD7		I/O	ST	Digital I/O.
PSP7		I/O	TTL	Parallel Slave Port data.
$\overline{SS2}$		I	TTL	SPI slave select input.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; I^2C™ = I^2C/SMBus input buffer

Note 1: Default assignment for ECCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for ECCP2 when Configuration bit, CCP2MX, is cleared.

TABLE 1-2: PIC18F6628/6723 (64-PIN) PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTF is a bidirectional I/O port.
RF0/AN5	18			
RF0		I/O	ST	Digital I/O.
AN5		I	Analog	Analog input 5.
RF1/AN6/C2OUT	17			
RF1		I/O	ST	Digital I/O.
AN6		I	Analog	Analog input 6.
C2OUT		O	—	Comparator 2 output.
RF2/AN7/C1OUT	16			
RF2		I/O	ST	Digital I/O.
AN7		I	Analog	Analog input 7.
C1OUT		O	—	Comparator 1 output.
RF3/AN8	15			
RF3		I/O	ST	Digital I/O.
AN8		I	Analog	Analog input 8.
RF4/AN9	14			
RF4		I/O	ST	Digital I/O.
AN9		I	Analog	Analog input 9.
RF5/AN10/CVREF	13			
RF5		I/O	ST	Digital I/O.
AN10		I	Analog	Analog input 10.
CVREF		O	Analog	Comparator reference voltage output.
RF6/AN11	12			
RF6		I/O	ST	Digital I/O.
AN11		I	Analog	Analog input 11.
RF7/$\overline{SS1}$	11			
RF7		I/O	ST	Digital I/O.
$\overline{SS1}$		I	TTL	SPI slave select input.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; I^2C™ = I^2C/SMBus input buffer

Note 1: Default assignment for ECCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for ECCP2 when Configuration bit, CCP2MX, is cleared.

TABLE 1-3: PIC18F8628/8723 (80-PIN) PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTB is a bidirectional I/O port. PORTB can be software programmed for internal weak pull-ups on all inputs.
RB0/INT0/FLT0	58			
RB0		I/O	TTL	Digital I/O.
INT0		I	ST	External interrupt 0.
FLT0		I	ST	PWM Fault input for ECCPx.
RB1/INT1	57			
RB1		I/O	TTL	Digital I/O.
INT1		I	ST	External interrupt 1.
RB2/INT2	56			
RB2		I/O	TTL	Digital I/O.
INT2		I	ST	External interrupt 2.
RB3/INT3/ECCP2/P2A	55			
RB3		I/O	TTL	Digital I/O.
INT3		I	ST	External interrupt 3.
ECCP2(1)		O	—	Enhanced Capture 2 input/Compare 2 output/ PWM2 output.
P2A(1)		O	—	ECCP2 PWM output A.
RB4/KBI0	54			
RB4		I/O	TTL	Digital I/O.
KBI0		I	TTL	Interrupt-on-change pin.
RB5/KBI1/PGM	53			
RB5		I/O	TTL	Digital I/O.
KBI1		I	TTL	Interrupt-on-change pin.
PGM		I/O	ST	Low-Voltage ICSP™ Programming enable pin.
RB6/KBI2/PGC	52			
RB6		I/O	TTL	Digital I/O.
KBI2		I	TTL	Interrupt-on-change pin.
PGC		I/O	ST	In-Circuit Debugger and ICSP™ programming clock pin.
RB7/KBI3/PGD	47			
RB7		I/O	TTL	Digital I/O.
KBI3		I	TTL	Interrupt-on-change pin.
PGD		I/O	ST	In-Circuit Debugger and ICSP programming data pin.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; I^2C™/SMB = I^2C/SMBus input buffer

Note 1: Alternate assignment for ECCP2 when Configuration bit, CCP2MX, is cleared (all operating modes except Microcontroller mode).

2: Default assignment for ECCP2 in all operating modes (CCP2MX is set).

3: Alternate assignment for ECCP2 when CCP2MX is cleared (Microcontroller mode only).

4: Default assignment for P1B/P1C/P3B/P3C (ECCPMX is set).

5: Alternate assignment for P1B/P1C/P3B/P3C (ECCPMX is clear).

TABLE 1-3: PIC18F8628/8723 (80-PIN) PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTD is a bidirectional I/O port.
RD0/AD0/PSP0	72			
RD0		I/O	ST	Digital I/O.
AD0		I/O	TTL	External memory address/data 0.
PSP0		I/O	TTL	Parallel Slave Port data.
RD1/AD1/PSP1	69			
RD1		I/O	ST	Digital I/O.
AD1		I/O	TTL	External memory address/data 1.
PSP1		I/O	TTL	Parallel Slave Port data.
RD2/AD2/PSP2	68			
RD2		I/O	ST	Digital I/O.
AD2		I/O	TTL	External memory address/data 2.
PSP2		I/O	TTL	Parallel Slave Port data.
RD3/AD3/PSP3	67			
RD3		I/O	ST	Digital I/O.
AD3		I/O	TTL	External memory address/data 3.
PSP3		I/O	TTL	Parallel Slave Port data.
RD4/AD4/PSP4/SDO2	66			
RD4		I/O	ST	Digital I/O.
AD4		I/O	TTL	External memory address/data 4.
PSP4		I/O	TTL	Parallel Slave Port data.
SDO2		O	—	SPI data out.
RD5/AD5/PSP5/ SDI2/SDA2	65			
RD5		I/O	ST	Digital I/O.
AD5		I/O	TTL	External memory address/data 5.
PSP5		I/O	TTL	Parallel Slave Port data.
SDI2		I	ST	SPI data in.
SDA2		I/O	I^2C/SMB	I^2C™ data I/O.
RD6/AD6/PSP6/ SCK2/SCL2	64			
RD6		I/O	ST	Digital I/O.
AD6		I/O	TTL	External memory address/data 6.
PSP6		I/O	TTL	Parallel Slave Port data.
SCK2		I/O	ST	Synchronous serial clock input/output for SPI mode.
SCL2		I/O	I^2C/SMB	Synchronous serial clock input/output for I^2C mode.
RD7/AD7/PSP7/$\overline{SS2}$	63			
RD7		I/O	ST	Digital I/O.
AD7		I/O	TTL	External memory address/data 7.
PSP7		I/O	TTL	Parallel Slave Port data.
$\overline{SS2}$		I	TTL	SPI slave select input.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; I^2C™/SMB = I^2C/SMBus input buffer

Note 1: Alternate assignment for ECCP2 when Configuration bit, CCP2MX, is cleared (all operating modes except Microcontroller mode).

2: Default assignment for ECCP2 in all operating modes (CCP2MX is set).

3: Alternate assignment for ECCP2 when CCP2MX is cleared (Microcontroller mode only).

4: Default assignment for P1B/P1C/P3B/P3C (ECCPMX is set).

5: Alternate assignment for P1B/P1C/P3B/P3C (ECCPMX is clear).

TABLE 1-3: PIC18F8628/8723 (80-PIN) PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTJ is a bidirectional I/O port.
RJ0/ALE	62			
RJ0		I/O	ST	Digital I/O.
ALE		O	—	External memory address latch enable.
RJ1/$\overline{OE}$	61			
RJ1		I/O	ST	Digital I/O.
$\overline{OE}$		O	—	External memory output enable.
RJ2/$\overline{WRL}$	60			
RJ2		I/O	ST	Digital I/O.
$\overline{WRL}$		O	—	External memory write low control.
RJ3/$\overline{WRH}$	59			
RJ3		I/O	ST	Digital I/O.
$\overline{WRH}$		O	—	External memory write high control.
RJ4/BA0	39			
RJ4		I/O	ST	Digital I/O.
BA0		O	—	External memory byte address 0 control.
RJ5/$\overline{CE}$	40			
RJ4		I/O	ST	Digital I/O
$\overline{CE}$		O	—	External memory chip enable control.
RJ6/$\overline{LB}$	41			
RJ6		I/O	ST	Digital I/O.
$\overline{LB}$		O	—	External memory low byte control.
RJ7/$\overline{UB}$	42			
RJ7		I/O	ST	Digital I/O.
$\overline{UB}$		O	—	External memory high byte control.
VSS	11, 31, 51, 70	P	—	Ground reference for logic and I/O pins.
VDD	12, 32, 48, 71	P	—	Positive supply for logic and I/O pins.
AVSS	26	P	—	Ground reference for analog modules.
AVDD	25	P	—	Positive supply for analog modules.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; I^2C™/SMB = I^2C/SMBus input buffer

Note 1: Alternate assignment for ECCP2 when Configuration bit, CCP2MX, is cleared (all operating modes except Microcontroller mode).

2: Default assignment for ECCP2 in all operating modes (CCP2MX is set).

3: Alternate assignment for ECCP2 when CCP2MX is cleared (Microcontroller mode only).

4: Default assignment for P1B/P1C/P3B/P3C (ECCPMX is set).

5: Alternate assignment for P1B/P1C/P3B/P3C (ECCPMX is clear).

REGISTER 2-3: ADCON2: A/D CONTROL REGISTER 2

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADFM	—	ACQT2	ACQT1	ACQT0	ADCS2	ADCS1	ADCS0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **ADFM:** A/D Result Format Select bit
1 = Right justified
0 = Left justified

bit 6 **Unimplemented:** Read as '0'

bit 5-3 **ACQT2:ACQT0:** A/D Acquisition Time Select bits
111 = 20 TAD
110 = 16 TAD
101 = 12 TAD
100 = 8 TAD
011 = 6 TAD
010 = 4 TAD
001 = 2 TAD
000 = 0 TAD(1)

bit 2-0 **ADCS2:ADCS0:** A/D Conversion Clock Select bits
111 = FRC (clock derived from A/D RC oscillator)(1)
110 = FOSC/64
101 = FOSC/16
100 = FOSC/4
011 = FRC (clock derived from A/D RC oscillator)(1)
010 = FOSC/32
001 = FOSC/8
000 = FOSC/2

Note 1: If the A/D FRC clock source is selected, a delay of one TCY (instruction cycle) is added before the A/D clock starts. This allows the SLEEP instruction to be executed before starting a conversion.

2.1 A/D Acquisition Requirements

For the A/D Converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 2-3. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor, CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD). The source impedance affects the offset voltage at the analog input (due to pin leakage current). **The maximum recommended impedance for analog sources is 2.5 kΩ**. After the analog input channel is selected (changed), the channel must be sampled for at least the minimum acquisition time before starting a conversion.

Note:	When the conversion is started, the holding capacitor is disconnected from the input pin.

To calculate the minimum acquisition time, Equation 2-1 may be used. This equation assumes that 1/2 LSb error is used (4096 steps for the 12-bit A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified resolution.

Example 2-3 shows the calculation of the minimum required acquisition time, TACQ. This calculation is based on the following application system assumptions:

CHOLD	=	25 pF
Rs	=	2.5 kΩ
Conversion Error	≤	1/2 LSb
VDD	=	3V → Rss = 4 kΩ
Temperature	=	85°C (system max.)

EQUATION 2-1: ACQUISITION TIME

$$T_{ACQ} = \text{Amplifier Settling Time} + \text{Holding Capacitor Charging Time} + \text{Temperature Coefficient}$$
$$= T_{AMP} + T_C + T_{COFF}$$

EQUATION 2-2: A/D MINIMUM CHARGING TIME

$$V_{HOLD} = (V_{REF} - (V_{REF}/4096)) \cdot (1 - e^{(-T_C/C_{HOLD}(R_{IC} + R_{SS} + R_S))})$$
or
$$T_C = -(C_{HOLD})(R_{IC} + R_{SS} + R_S) \ln(1/4096)$$

EQUATION 2-3: CALCULATING THE MINIMUM REQUIRED ACQUISITION TIME

$$T_{ACQ} = T_{AMP} + T_C + T_{COFF}$$
$$T_{AMP} = 0.2\ \mu s$$
$$T_{COFF} = (\text{Temp} - 25°C)(0.02\ \mu s/°C)$$
$$(85°C - 25°C)(0.02\ \mu s/°C)$$
$$1.2\ \mu s$$

Temperature coefficient is only required for temperatures > 25°C. Below 25°C, $T_{COFF} = 0\ \mu s$.

$$T_C = -(C_{HOLD})(R_{IC} + R_{SS} + R_S) \ln(1/4096)\ \mu s$$
$$-(25\ pF)\ (1\ k\Omega + 4\ k\Omega + 2.5\ k\Omega) \ln(0.0002441)\ \mu s$$
$$1.56\ \mu s$$

$$T_{ACQ} = 0.2\ \mu s + 1.56\ \mu s + 1.2\ \mu s$$
$$2.96\ \mu s$$

2.2 Selecting and Configuring Acquisition Time

The ADCON2 register allows the user to select an acquisition time that occurs each time the GO/DONE bit is set. It also gives users the option to use an automatically determined acquisition time.

Acquisition time may be set with the ACQT2:ACQT0 bits (ADCON2<5:3>), which provide a range of 2 to 20 TAD. When the GO/DONE bit is set, the A/D module continues to sample the input for the selected acquisition time, then automatically begins a conversion. Since the acquisition time is programmed, there may be no need to wait for an acquisition time between selecting a channel and setting the GO/DONE bit.

Manual acquisition is selected when ACQT2:ACQT0 = 000. When the GO/DONE bit is set, sampling is stopped and a conversion begins. The user is responsible for ensuring the required acquisition time has passed between selecting the desired input channel and setting the GO/DONE bit. This option is also the default Reset state of the ACQT2:ACQT0 bits and is compatible with devices that do not offer programmable acquisition times.

In either case, when the conversion is completed, the GO/DONE bit is cleared, the ADIF flag is set and the A/D begins sampling the currently selected channel again. If an acquisition time is programmed, there is nothing to indicate if the acquisition time has ended or if the conversion has begun.

2.3 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires 13 TAD per 12-bit conversion. The source of the A/D conversion clock is software selectable. There are seven possible options for TAD:

- 2 TOSC
- 4 TOSC
- 8 TOSC
- 16 TOSC
- 32 TOSC
- 64 TOSC
- Internal RC Oscillator

For correct A/D conversions, the A/D conversion clock (TAD) must be as short as possible, but greater than the minimum TAD (see parameter 130 for more information).

Table 2-1 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

TABLE 2-1: TAD vs. DEVICE OPERATING FREQUENCIES

A/D Clock Source (TAD)		Assumes TAD Min. = 0.8 μs
Operation	**ADCS2:ADCS0**	**Maximum FOSC**
2 TOSC	000	2.50 MHz
4 TOSC	100	5.00 MHz
8 TOSC	001	10.00 MHz
16 TOSC	101	20.00 MHz
32 TOSC	010	40.00 MHz
64 TOSC	110	40.00 MHz
RC(1)	x11	1.00 MHz(2)

Note 1: The RC source has a typical TAD time of 2.5 μs.

2: For device frequencies above 1 MHz, the device must be in Sleep for the entire conversion or a FOSC divider should be used instead; otherwise, the A/D accuracy specification may not be met.

2.6 A/D Conversions

Figure 2-4 shows the operation of the A/D Converter after the GO/$\overline{\text{DONE}}$ bit has been set and the ACQT2:ACQT0 bits are cleared. A conversion is started after the following instruction to allow entry into Sleep mode before the conversion begins.

Figure 2-5 shows the operation of the A/D Converter after the GO/$\overline{\text{DONE}}$ bit has been set, the ACQT2:ACQT0 bits are set to '010' and a 4 TAD acquisition time has been selected before the conversion starts.

Clearing the GO/$\overline{\text{DONE}}$ bit during a conversion will abort the current conversion. The A/D Result register pair will NOT be updated with the partially completed A/D conversion sample. This means the ADRESH:ADRESL registers will continue to contain the value of the last completed conversion (or the last value written to the ADRESH:ADRESL registers).

After the A/D conversion is completed or aborted, a 2 TCY wait is required before the next acquisition can be started. After this wait, acquisition on the selected channel is automatically started.

Note: The GO/$\overline{\text{DONE}}$ bit should **NOT** be set in the same instruction that turns on the A/D. Code should wait at least 2 μs after enabling the A/D before beginning an acquisition and conversion cycle.

2.7 Discharge

The discharge phase is used to initialize the value of the holding capacitor. The array is discharged before every sample. This feature helps to optimize the unity gain amplifier, as the circuit always needs to charge the capacitor array, rather than charge/discharge based on previous measure values.

FIGURE 2-4: A/D CONVERSION TAD CYCLES (ACQT<2:0> = 000, TACQ = 0)

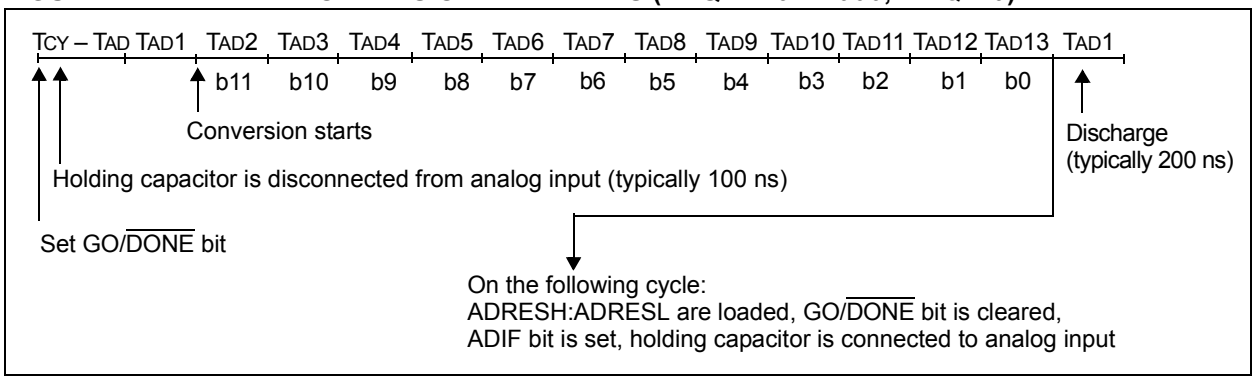
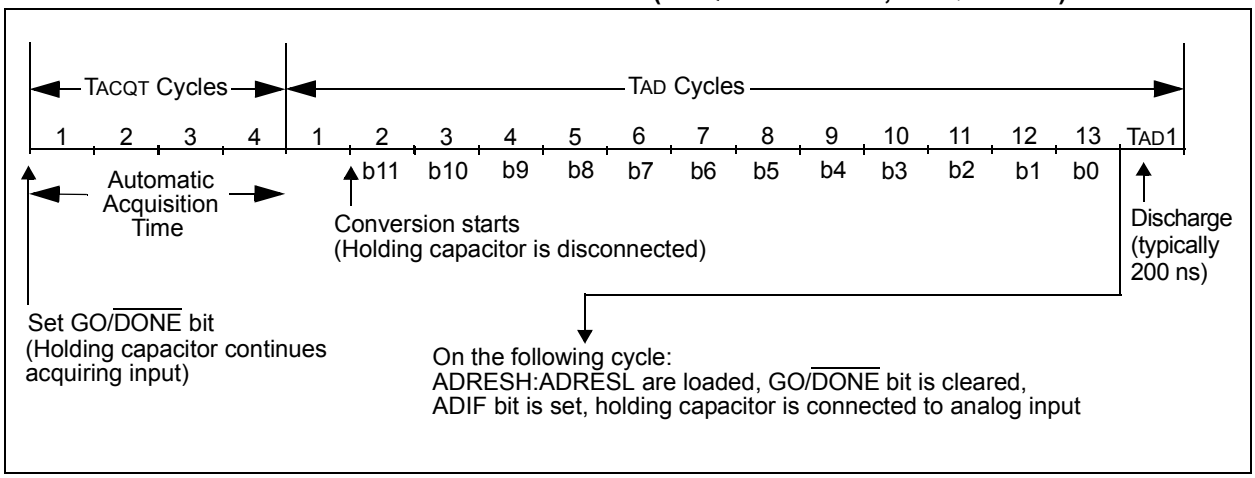


FIGURE 2-5: A/D CONVERSION TAD CYCLES (ACQT<2:0> = 010, TACQ = 4 TAD)



4.0 ELECTRICAL CHARACTERISTICS

Note: Other than some basic data, this section documents only the PIC18F8723 family's specifications that differ from those of the PIC18F8722 family devices. For detailed information on the electrical specifications shared by the PIC18F8723 family and PIC18F8722 family devices, see the *"PIC18F8722 Family Data Sheet"* (DS39646).

Absolute Maximum Ratings(†)

Ambient temperature under bias ..... -40°C to +125°C

Storage temperature ..... -65°C to +150°C

Voltage on any pin with respect to V_{SS} (except V_{DD} and $\overline{MCLR}$) ..... -0.3V to (V_{DD} + 0.3V)

Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +7.5V

Voltage on $\overline{MCLR}$ with respect to V_{SS} **(Note 2)** ..... 0V to +13.25V

Total power dissipation **(Note 1)** 1.0W

Maximum current out of V_{SS} pin ..... 300 mA

Maximum current into V_{DD} pin ..... 250 mA

Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ±20 mA

Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ±20 mA

Maximum output current sunk by any I/O pin ..... 25 mA

Maximum output current sourced by any I/O pin ..... 25 mA

Maximum current sunk by all ports ..... 200 mA

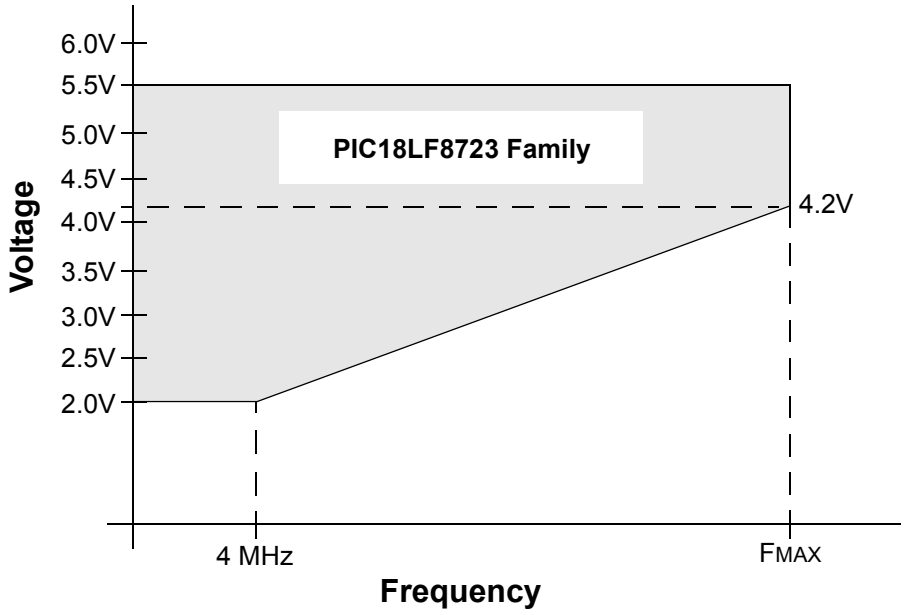
Maximum current sourced by all ports ..... 200 mA

Note 1: Power dissipation is calculated as follows:
$P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

2: Voltage spikes below V_{SS} at the RG5/$\overline{MCLR}$/V_{PP} pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the RG5/$\overline{MCLR}$/V_{PP} pin, rather than pulling this pin directly to V_{SS}.

† **NOTICE:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

FIGURE 4-3: PIC18LF8723 FAMILY VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL)



In 8-Bit External Memory mode:
F_{MAX} = (9.55 MHz/V) ($V_{DDAPPMIN}$ – 2.0V) + 4 MHz, if $V_{DDAPPMIN} \leq$ 4.2V;
F_{MAX} = 25 MHz, if $V_{DDAPPMIN}$ > 4.2V.

In all other modes:
F_{MAX} = (16.36 MHz/V) ($V_{DDAPPMIN}$ – 2.0V) + 4 MHz;
F_{MAX} = 40 MHz, if $V_{DDAPPMIN}$ > 4.2V.

Note: $V_{DDAPPMIN}$ is the minimum voltage of the PIC® device in the application.

NOTES:

5.0 PACKAGING INFORMATION

For packaging information, see the *"PIC18F8722 Family Data Sheet"* (DS39646).

NOTES:

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